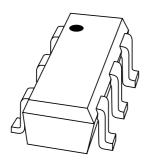
DISCRETE SEMICONDUCTORS

DATA SHEET



BGA2711MMIC wideband amplifier

Product specification Supersedes data of 2001 Apr 04 2001 Oct 19





MMIC wideband amplifier

BGA2711

FEATURES

- Internally matched to 50 Ω
- Very wide frequency range
- · Very flat gain
- Unconditionally stable.

APPLICATIONS

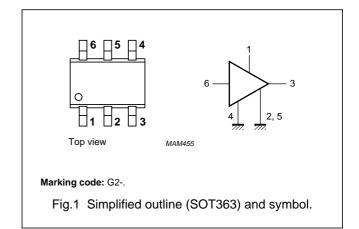
- · Cable systems
- · LNB IF amplifiers
- · General purpose
- ISM.

DESCRIPTION

Silicon Monolithic Microwave Integrated Circuit (MMIC) wideband amplifier with internal matching circuit in a 6-pin SOT363 SMD plastic package.

PINNING

| PIN | DESCRIPTION |
|------|-------------|
| 1 | Vs |
| 2, 5 | GND2 |
| 3 | RF out |
| 4 | GND1 |
| 6 | RF in |



QUICK REFERENCE DATA

| SYMBOL | PARAMETER | CONDITIONS | TYP. | MAX. | UNIT |
|--------------------------------|----------------------|------------|------|------|------|
| Vs | DC supply voltage | | 5 | 6 | V |
| I _S | DC supply current | | 12.6 | _ | mA |
| s ₂₁ ² | insertion power gain | f = 1 GHz | 13.1 | _ | dB |
| NF | noise figure | f = 1 GHz | 4.8 | _ | dB |
| P _{L(sat)} | saturated load power | f = 1 GHz | 2.8 | _ | dBm |

CAUTION

This product is supplied in anti-static packing to prevent damage caused by electrostatic discharge during transport and handling. For further information, refer to Philips specs.: SNW-EQ-608, SNW-FQ-302A and SNW-FQ-302B.

MMIC wideband amplifier

BGA2711

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134)

| SYMBOL | PARAMETER | CONDITIONS | MIN. | MAX. | UNIT |
|------------------|--------------------------------|------------------------|------|------|------|
| V _S | DC supply voltage | RF input AC coupled | _ | 6 | V |
| I _S | supply current | | _ | 20 | mA |
| P _{tot} | total power dissipation | T _s ≤ 80 °C | _ | 200 | mW |
| T _{stg} | storage temperature | | -65 | +150 | °C |
| Tj | operating junction temperature | | _ | 150 | °C |
| P _D | maximum drive power | | _ | 10 | dBm |

THERMAL RESISTANCE

| SYMBOL | PARAMETER | CONDITIONS | VALUE | UNIT |
|---------------------|--|---|-------|------|
| R _{th j-s} | thermal resistance from junction to solder point | $P_{tot} = 200 \text{ mW}; T_s \le 80 ^{\circ}\text{C}$ | 300 | K/W |

CHARACTERISTICS

 V_S = 5 V; I_S = 12.6 mA; f = 1 GHz; T_j = 25 °C unless otherwise specified.

| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|--------------------------------|------------------------|--|------|------|------|------|
| I _S | supply current | | 10 | 12.6 | 16 | mA |
| s ₂₁ ² | insertion power gain | f = 1 GHz | _ | 13.1 | _ | dB |
| | | f = 2 GHz | _ | 13.9 | _ | dB |
| R _{L IN} | return losses input | f = 1 GHz | _ | 11 | _ | dB |
| | | f = 2 GHz | _ | 10 | _ | dB |
| R _{L OUT} | return losses output | f = 1 GHz | _ | 18 | _ | dB |
| | | f = 2 GHz | _ | 13 | _ | dB |
| NF | noise figure | f = 1 GHz | _ | 4.8 | _ | dB |
| | | f = 2 GHz | _ | 4.8 | _ | dB |
| BW | bandwidth | at $ s_{21} ^2$ –3 dB below flat gain at 1 GHz | _ | 3.6 | _ | GHz |
| P _{L(sat)} | saturated load power | f = 1 GHz | _ | 2.8 | _ | dBm |
| | | f = 2 GHz | _ | 0.6 | _ | dBm |
| P _{L 1 dB} | load power | at 1 dB gain compression; f = 1 GHz | _ | -0.7 | _ | dBm |
| | | at 1 dB gain compression; f = 2 GHz | _ | -1.8 | _ | dBm |
| IP3 _(in) | input intercept point | f = 1 GHz | _ | -4.8 | _ | dBm |
| | | f = 2 GHz | _ | -8.5 | _ | dBm |
| IP3 _(out) | output intercept point | f = 1 GHz | _ | 8.3 | _ | dBm |
| | | f = 2 GHz | _ | 5.4 | _ | dBm |

MMIC wideband amplifier

BGA2711

APPLICATION INFORMATION

Figure 2 shows a typical application circuit for the BGA2711 MMIC. The device is internally matched to 50 Ω , and therefore does not need any external matching. The value of the input and output DC blocking capacitors C2, C3 should be not more than 100 pF for applications above 100 MHz. However, when the device is operated below 100 MHz, the capacitor value should be increased.

The 22 nF supply decoupling capacitor, C1 should be located as closely as possible to the MMIC.

Separate paths must be used for the ground planes of the ground pins GND1, GND2, and these paths must be as short as possible. When using vias, use multiple vias per pin in order to limit ground path inductance.

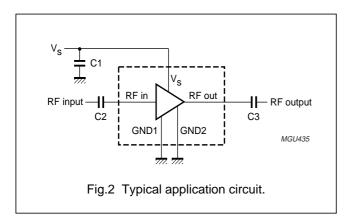
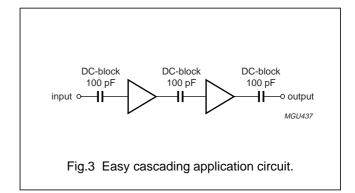


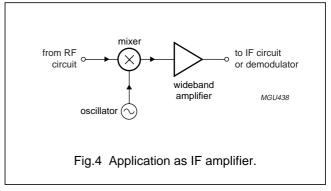
Figure 3 shows two cascaded MMICs. This configuration doubles overall gain while preserving broadband characteristics. Supply decoupling and grounding conditions for each MMIC are the same as those for the circuit of Fig.2.

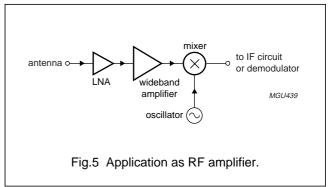
The excellent wideband characteristics of the MMIC make it and ideal building block in IF amplifier applications such as LBNs (see Fig.4).

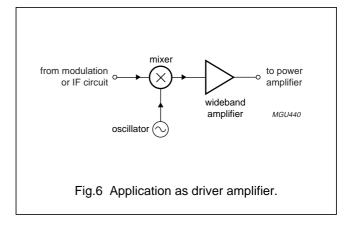
As a buffer amplifier between an LNA and a mixer in a receiver circuit, the MMIC offers an easy matching, low noise solution (see Fig.5).

In Fig.6 the MMIC is used as a driver to the power amplifier in part of a transmitter circuit. Good linear performance and matched input and output offer quick design solutions in such applications.



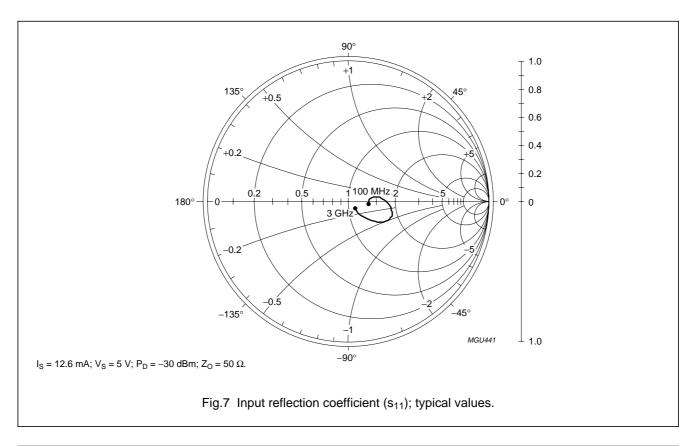


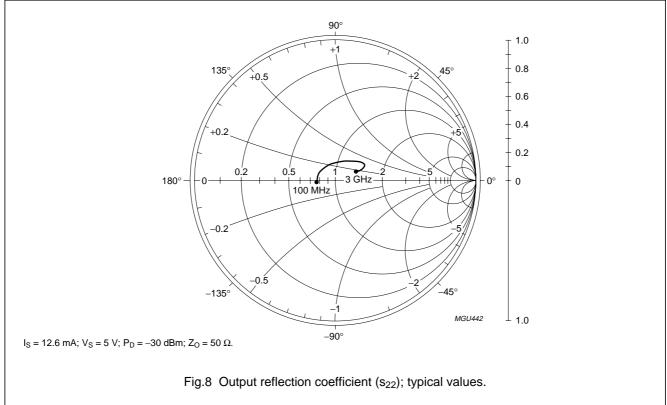




MMIC wideband amplifier

BGA2711





MMIC wideband amplifier

BGA2711

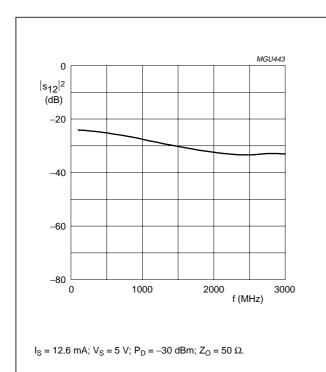


Fig.9 Isolation ($|s_{12}|^2$) as a function of frequency; typical values.

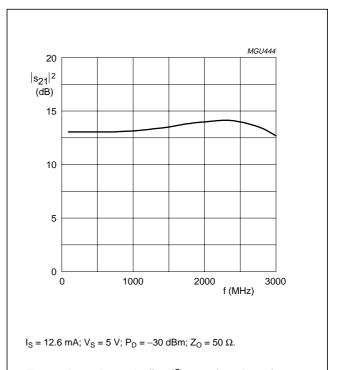


Fig.10 Insertion gain $(|s_{21}|^2)$ as a function of frequency; typical values.

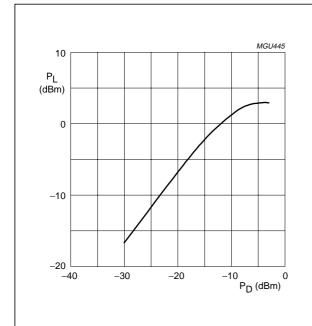


Fig.11 Load power as a function of drive power at 1 GHz; typical values.

 $V_S = 5 \text{ V}; f = 1 \text{ GHz}; Z_O = 50 \Omega.$

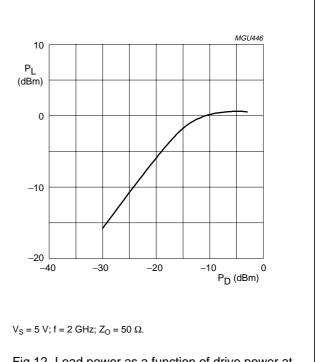
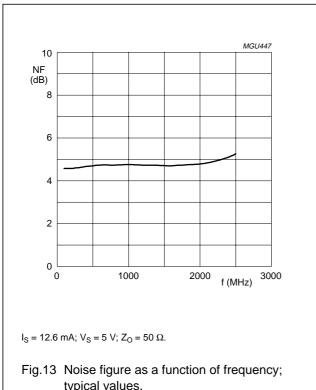


Fig.12 Load power as a function of drive power at 2 GHz; typical values.

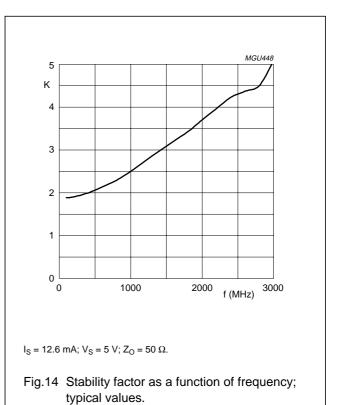
Product specification Philips Semiconductors

MMIC wideband amplifier

BGA2711



typical values.



Scattering parameters: I_S = 12.6 mA; P_D = –30 dBm; Z_O = 50 Ω ; T_{amb} = 25 $^{\circ}$ C

| | S ₁₁ | | s ₂₁ | | S ₁₂ | | S ₂₂ | |
|-------|-------------------|----------------|-------------------|----------------|-------------------|----------------|-------------------|----------------|
| (MHz) | MAGNITUDE (ratio) | ANGLE (deg) |
| 100 | 0.14563 | -3.502 | 4.4867 | -1.843 | 0.06220 | -2.939 | 0.13029 | -174.50 |
| 200 | 0.15253 | 5.557 | 4.4944 | -6.788 | 0.06117 | -8.095 | 0.12640 | 169.58 |
| 400 | 0.18735 | 10.06 | 4.4841 | -15.22 | 0.05751 | -16.61 | 0.11957 | 148.02 |
| 600 | 0.22695 | 8.206 | 4.4862 | -22.94 | 0.05240 | -22.85 | 0.11288 | 126.58 |
| 800 | 0.26122 | 2.635 | 4.4985 | -30.57 | 0.04744 | -27.72 | 0.11286 | 104.24 |
| 1000 | 0.28776 | -2.465 | 4.5390 | -38.34 | 0.04187 | -31.17 | 0.12236 | 82.570 |
| 1200 | 0.30888 | -8.179 | 4.6052 | -46.14 | 0.03666 | -32.98 | 0.14066 | 65.815 |
| 1400 | 0.32055 | -13.16 | 4.6862 | -54.45 | 0.03251 | -33.25 | 0.16341 | 53.911 |
| 1600 | 0.32492 | -17.85 | 4.7929 | -63.29 | 0.02903 | -32.38 | 0.18689 | 45.122 |
| 1800 | 0.31849 | -22.43 | 4.9219 | -72.67 | 0.02624 | -29.24 | 0.20662 | 38.894 |
| 2000 | 0.30085 | -26.75 | 4.9973 | -83.08 | 0.02395 | -26.62 | 0.22092 | 33.706 |
| 2200 | 0.27106 | -31.57 | 5.0755 | -93.96 | 0.02228 | -22.20 | 0.22754 | 29.699 |
| 2400 | 0.23157 | -35.78 | 5.0668 | -106.1 | 0.02134 | -17.95 | 0.22679 | 26.622 |
| 2600 | 0.18594 | -40.38 | 4.9143 | -118.1 | 0.02176 | -13.86 | 0.21806 | 23.868 |
| 2800 | 0.13159 | -44.34 | 4.6797 | -129.6 | 0.02276 | -12.70 | 0.19660 | 22.060 |
| 3000 | 0.07266 | -41.76 | 4.3139 | -140.5 | 0.02241 | -17.06 | 0.16355 | 22.273 |

2001 Oct 19 7

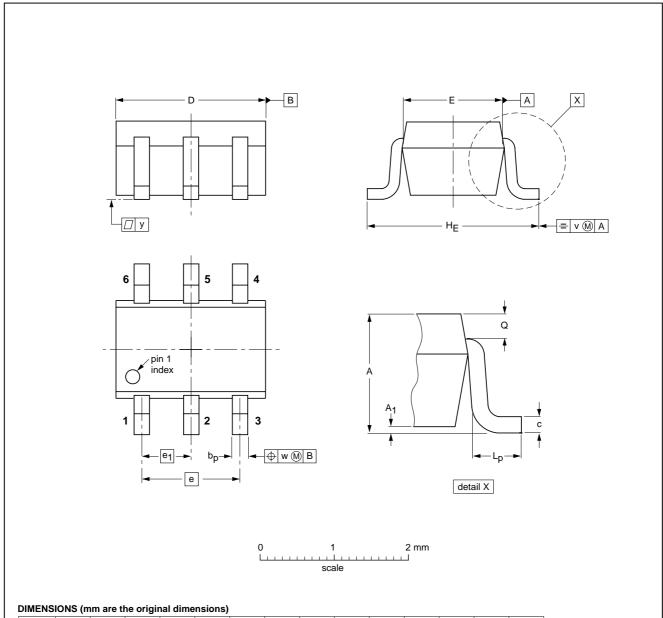
MMIC wideband amplifier

BGA2711

PACKAGE OUTLINE

Plastic surface mounted package; 6 leads

SOT363



| UNIT | Α | A ₁ max | bp | С | D | E | е | e ₁ | HE | Lp | Q | v | w | у |
|------|------------|-----------------------|--------------|--------------|------------|--------------|-----|----------------|------------|--------------|--------------|-----|-----|-----|
| mm | 1.1 0.8 | 0.1 | 0.30 0.20 | 0.25 0.10 | 2.2 1.8 | 1.35 1.15 | 1.3 | 0.65 | 2.2 2.0 | 0.45 0.15 | 0.25 0.15 | 0.2 | 0.2 | 0.1 |

| OUTLINE | | REFER | EUROPEAN | ISSUE DATE | | |
|---------|-----|-------|----------|------------|------------|------------|
| VERSION | IEC | JEDEC | EIAJ | | PROJECTION | ISSUE DATE |
| SOT363 | | | SC-88 | | | 97-02-28 |

MMIC wideband amplifier

BGA2711

DATA SHEET STATUS

| DATA SHEET STATUS(1) | PRODUCT STATUS ⁽²⁾ | DEFINITIONS |
|----------------------|----------------------------------|--|
| Objective data | Development | This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice. |
| Preliminary data | Qualification | This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product. |
| Product data | Production | This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A. |

Notes

- 1. Please consult the most recently issued data sheet before initiating or completing a design.
- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information — Applications that are described herein for any of these products are for illustrative purposes only. Philips Semiconductors make no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

DISCLAIMERS

Life support applications — These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips Semiconductors customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips Semiconductors for any damages resulting from such application.

Right to make changes — Philips Semiconductors reserves the right to make changes, without notice, in the products, including circuits, standard cells, and/or software, described or contained herein in order to improve design and/or performance. Philips Semiconductors assumes no responsibility or liability for the use of any of these products, conveys no licence or title under any patent, copyright, or mask work right to these products, and makes no representations or warranties that these products are free from patent, copyright, or mask work right infringement, unless otherwise specified.

MMIC wideband amplifier

BGA2711

NOTES

MMIC wideband amplifier

BGA2711

NOTES

Philips Semiconductors – a worldwide company

Contact information

For additional information please visit http://www.semiconductors.philips.com. Fax: +31 40 27 24825 For sales offices addresses send e-mail to: sales.addresses@www.semiconductors.philips.com.

© Koninklijke Philips Electronics N.V. 2001

SCA73

All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.

The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent- or other industrial or intellectual property rights.

Printed in The Netherlands

613516/02/pp12

Date of release: 2001 Oct 19

Document order number: 9397 750 08545

Let's make things better.

Philips Semiconductors



